

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.00319	1.33	0.04788
	Doped silicon	Silicon (Si)	7440-21-3	0.2363	98.67	3.55212
Subtotal				0.23949	100	3.6
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.01565	10.0	0.23522
	Silver alloy	Silver (Ag)	7440-22-4	0.00313	2.0	0.04704
	Lead alloy	Lead (Pb)	7439-92-1	0.1377	88.0	2.06997
Subtotal				0.15648	100	2.35223
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.27995	100.0	4.20829
	Subtotal				0.27995	100
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00977	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.00652	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.00977	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.03584	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	32.52037	99.81	488.8594
Subtotal				32.58227	100	489.79001
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.32264	100.0	4.85
	Subtotal				0.32264	100
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.31353	8.0	79.8752
	Filler	Silica fused	60676-86-0	53.79953	81.0	808.7364
	Metal hydroxide	Metal hydroxide		0.46493	0.7	6.98908
	Carbon Black	Carbon black	1333-86-4	0.19926	0.3	2.99532
	Polymer	Epoxy resin system		6.64192	10.0	99.844
Subtotal				66.41917	100	998.44
Total				100	100	1503.24053

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.